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8-bit Addressable Latch



ADE-205-480 (Z) 1st. Edition Sep. 2000

Description

The HD74HC259 has a single data input (D), 8 latch outputs (Q_0 - Q_7), 3 address inputs (A, B, and C), a common enable input (E), and a common clear input. To operate this device as an addressable latch, data is held on the D input, and the address of the latch into which the data is to be entered is held on the A, B and C inputs. When enable is taken low the data flows through to the addressed output. The data is stored when enable transitions from low to high. All unaddressed latches will remain unaffected. With enable in the high state the device is deselected, and all latches remain in their previous state, unaffected by changes on the data or address inputs. To eliminate the possibility of entering erroneous data into the latches, the enable should be held high (inactive) while the address lines are changing.

If enable is held high and clear is taken low all eight latches are cleared to a low state. If enable is low all latches except the addressed latch will be cleared. The addressed latch will instead follow the D input, effectively implementing a 3-to-8 line decoder.

Features

• High Speed Operation: t_{pd} (Data to Output) = 16 ns typ ($C_L = 50 \text{ pF}$)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2$ to 6 V

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

Inputs

Clear	G	Output of Addressed Latch	Each Other Output	Function
Н	L	D	Qio	Addressable latch
Н	Н	Qio	Qio	Memory
L	L	D	L	8-line demultiplexer
L	Н	L	L	Clear

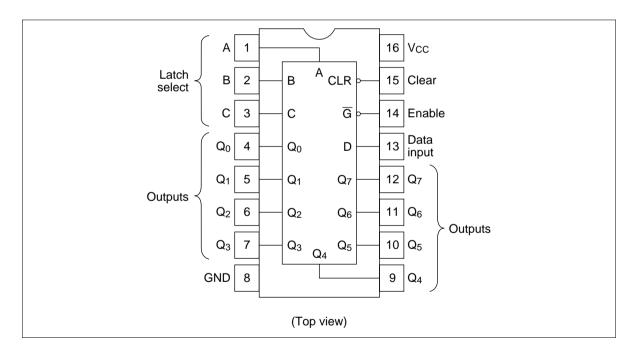
Select Inputs

С	В	Α	Latch Addressed
L	L	L	0
L	L	Н	1
L	Н	L	2
L	Н	Н	3
Н	L	L	4
Н	L	Н	5
Н	Н	L	6
Н	Н	Н	7

Notes: 1. D: the level at the data input

2. Qio: the level of Qi (i = 0, 1, ···7, as apropriate) before the indicated steady-state input conditions were established.

Pin Arrangement



DC Characteristics

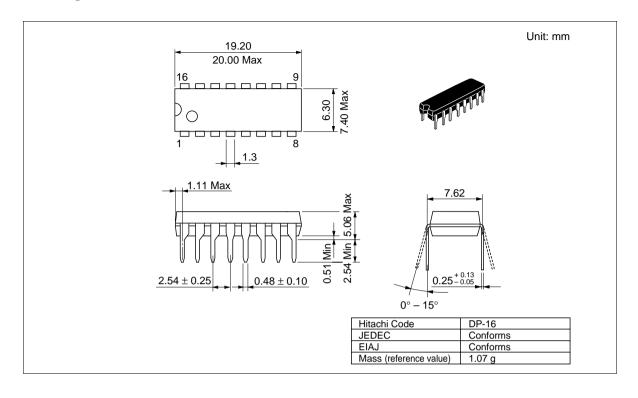
			Ta = 25°C		Ta = -40 to +85°C		_			
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	าร
Input voltage	V_{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	_		3.15	_	_		
		6.0	4.2	_	_	4.2	_	_		
	V _{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35	_		
		6.0	_	_	1.8	_	1.8	=		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	Vin = V _{IH} or V _{IL}	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_	=		
		6.0	5.9	6.0	_	5.9	_	=		
		4.5	4.18	_	_	4.13	_	=		$I_{OH} = -4 \text{ mA}$
		6.0	5.68	_	_	5.63	_	=		$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	Vin = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	_	0.0	0.1	_	0.1	_		
		6.0	_	0.0	0.1	_	0.1	_		
		4.5	_	_	0.26	_	0.33	=		I _{OL} = 4 mA
		6.0	_	_	0.26	_	0.33	=		I _{OL} = 5.2 mA
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GI	ND
Quiescent supply current	I _{cc}	6.0	_	_	4.0	_	40	μΑ	Vin = V _{CC} or Gi	ND, lout = $0 \mu A$

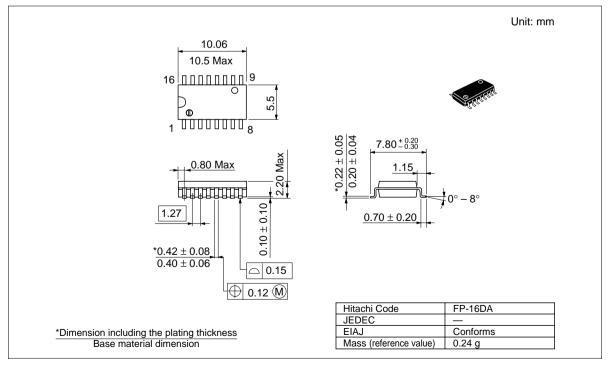
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Ta = -40 to $Ta = 25^{\circ}C$ +85°C

Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Propagation delay	t _{PHL}	2.0	_	_	185	_	230	ns	Data to output
time	t_{PLH}	4.5	_	16	37	_	46		
		6.0	_	_	31	_	39	=	
		2.0	_	_	215	_	270	_	Latch select to output
		4.5	_	20	43	_	54	=	
		6.0	_	_	37	_	46	=	
		2.0	_	_	200	_	250	_	Enable to output
		4.5	_	17	40	_	50	_	
		6.0	_	_	34	_	43	_	
	t _{PHL}	2.0	_	_	155	_	195	ns	Clear to output
		4.5	_	15	31	_	39	_	
		6.0	_	_	26	_	33	_	
Pulse width	t _w	2.0	80	_	_	100	_	ns	Clear, Enable
		4.5	16	6	_	20	_	_	
		6.0	14	_	_	17	_	_	
Setup time	t _{su}	2.0	100	_	_	125	_	ns	Latch select or data to enable
		4.5	20	5	_	25	_	_	
		6.0	17	_	_	21	_	_	
Hold time	t _h	2.0	5	_	_	5	_	ns	Latch select or data to enable
		4.5	5	-1	_	5		_	
		6.0	5	_	_	5	_	_	
Output rise/fall	t _{TLH}	2.0	_	_	75	_	95	ns	
time	t_{THL}	4.5	_	5	15	_	19	_	
		6.0	_	_	13	_	16	=	
Input capacitance	Cin	_	_	5	10	_	10	pF	

Package Dimensions





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